

TUSB3210

Universal Serial Bus General-Purpose Device Controller

Data Manual



Designing with this device may require extensive support. Before incorporating this device into a design, customers should contact TI or an Authorized TI Distributor.

IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgment, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Customers are responsible for their applications using TI components.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, license, warranty or endorsement thereof.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations and notices. Representation or reproduction of this information with alteration voids all warranties provided for an associated TI product or service, is an unfair and deceptive business practice, and TI is not responsible nor liable for any such use.

Resale of TI's products or services with <u>statements different from or beyond the parameters</u> stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service, is an unfair and deceptive business practice, and TI is not responsible nor liable for any such use.

Also see: Standard Terms and Conditions of Sale for Semiconductor Products, www.ti.com/sc/docs/stdterms.htm

Mailing Address:

Texas Instruments Post Office Box 655303 Dallas, Texas 75265

Contents

Se	ection		Title	Page
1	Intro	duction .		1–1
	1.1	Feature	s	1–1
	1.2	Function	nal Block Diagram	1–2
	1.3	Termina	ll Assignments	1–3
	1.4	Ordering	g Information	1–3
	1.5	Termina	Functions	1–4
2	Func	tional De	scription	2–1
	2.1	MCU M	emory Map	2–1
	2.2	Miscella	neous Registers	2–2
		2.2.1	TUSB3210 Boot Operation	2–2
		2.2.2	MCNFG: MCU Configuration Register	2–3
		2.2.3	PUR_n: GPIO Pullup Register for Port n (n = 0 to 3)	2–3
		2.2.4	INTCFG: Interrupt Configuration	2–3
		2.2.5	WDCSR: Watchdog Timer, Control, and Status Register .	2–4
		2.2.6	PCON: Power Control Register (at SFR 87h)	2–4
	2.3	Buffers	+ I/O RAM Map	2–4
	2.4	Endpoir	nt Descriptor Block (EDB-1 to EDB-3)	2–7
		2.4.1	OEPCNF_n: Output Endpoint Configuration	2–7
		2.4.2	OEPBBAX_n: Output Endpoint X-Buffer Base-Address	2–8
		2.4.3	OEPBCTX_n: Output Endpoint X Byte Count	2–8
		2.4.4	OEPBBAY_n: Output Endpoint Y-Buffer Base-Address	2–8
		2.4.5	OEPBCTY_n: Output Endpoint Y Byte Count	2–8
		2.4.6	OEPSIZXY_n: Output Endpoint X/Y Byte Count	2–9
		2.4.7	IEPCNF_n: Input Endpoint Configuration	2–9
		2.4.8	IEPBBAX_n: Input Endpoint X-Buffer Base-Address	2–9
		2.4.9	IEPBCTX_n: Input Endpoint X-Byte Base-Address	2-10
		2.4.10	IEPBBAY_n: Input Endpoint Y-Buffer Base-Address	2-10
		2.4.11	IEPBCTY_n: Input Endpoint Y Byte Count	2-10
		2.4.12	IEPSIZXY_n: Input Endpoint X/Y-Buffer Size	2–11
	2.5	Endpoir	nt-0 Descriptor Registers	2–11
		2.5.1	IEPCNFG_0: Input Endpoint-0 Configuration Register	2–11
		2.5.2	IEPBCNT_0: Input Endpoint-0 Byte Count Register	2–12
		2.5.3	OEPCNFG_0: Output Endpoint-0 Configuration	
			Register	
		2.5.4	OEPBCNT_0: Output Endpoint-0 Byte Count Register	
	2.6		egisters	
		2.6.1	FUNADR: Function Address Register	2-13

		2.6.2	USBSTA: USB Status Register 2–14
		2.6.3	USBMSK: USB Interrupt Mask Register 2–15
		2.6.4	USBCTL: USB Control Register 2–16
		2.6.5	VIDSTA: VID/PID Status Register
	2.7	Function	Reset and Power-Up Reset Interconnect 2–17
	2.8	Pullup R	esistor Connect/Disconnect
	2.9	8052 Inte	errupt and Status Registers 2–18
		2.9.1	8052 Standard Interrupt Enable Register
		2.9.2	Additional Interrupt Sources 2–19
		2.9.3	VECINT: Vector Interrupt Register
		2.9.4	Logical Interrupt Connection Diagram (INTO) 2–21
		2.9.5	P2[7:0] Interrupt (INT1)
	2.10	I2C Regi	isters 2–22
		2.10.1	I2CSTA: I2C Status and Control Register 2–22
		2.10.2	I2CADR: I2C Address Register 2–23
		2.10.3	I2CDAI: I2C Data-Input Register 2–23
		2.10.4	I2CDAO: I2C Data-Output Register
	2.11	Read/Wr	rite Operations 2–23
		2.11.1	Read Operation (Serial EEPROM)
		2.11.2	Current Address Read Operation 2–24
		2.11.3	Sequential Read Operation
		2.11.4	Write Operation (Serial EEPROM)
		2.11.5	Page Write Operation 2–26
3	Electr	-	ifications 3–1
	3.1		Maximum Ratings Over Operating Free-air Temperature . 3–1
	3.2		cial Operating Condition 3-1
	3.3	Electrica GND = 0	I Characteristics, T _A = 25°C, V _{CC} = 3.3 V ± 0.3 V, 0 V
4	Applic		4–1
	4.1		es 4–1
	4.2	Reset Ti	ming 4–2
5	Mecha	anical Dat	ta 5–1

List of Illustrations

Figu	re Title	Page
1–1	TUSB3210 Block Diagram	1–2
2–1	MCU Memory Map (TUSB3210)	2–1
2–2	MCU Memory Map (ROM Version)	2–2
2–3	Reset Diagram	2–17
2–4	Pullup Resistor Connect/Disconnect Circuit	2–18
2–5	Internal Vector Interrupt (EX0)	2–21
2–6	P2[7:0] Input Port Interrupt Generation	2–21
4–1	Example LED Connection	4–1
4–2	Partial Connection Bus Power Mode	4–1
4–3	Upstream Connection (a) Non-switching Power Mode (b) Switching Power Mode	4–2
4–4	Downstream Connection-(Only One Port Shown)	4–2
4–5	Reset Timing	4–2
	List of Tables	
Tabl	e Title	Page
2–1	XDATA Space	2–5
	Memory Mapped Registers Summary (XDATA Range = FF80 \rightarrow FFFF) \hdots	
	EDB and Buffer Allocations in XDATA	
	EDB Entries in RAM (n = 1 to 3)	
	Input/Output EDB-0 Registers	
	External Pins Mapping to S[3:0] in VIDSTA Register	
	Vector Interrupt Values	
_ 0	voto: interrupt values	0

1 Introduction

The TUSB3210 has $8k \times 8$ RAM space for application development. A ROM based version of the TUSB3210 has $8k \times 8$ ROM space for predeveloped customer specific production applications. In addition, the programmability of the TUSB3210 makes it flexible enough to use for various other general USB I/O applications. Unique vendor identification and product identification (VID/PID) may be selected without the use of an external EEPROM. Using a 12 MHz crystal, the onboard oscillator generates the internal system clocks. The device may be programmed via an inter-IC (I²C) serial interface at power on from an EEPROM, or optionally, the application firmware may be downloaded from a host PC via USB. The popular 8052-based microprocessor allows several third party standard tools to be used for application development. In addition, the vast amounts of application code available in the general market may also be utilized (this may or may not require some code modification due to hardware variations).

1.1 Features

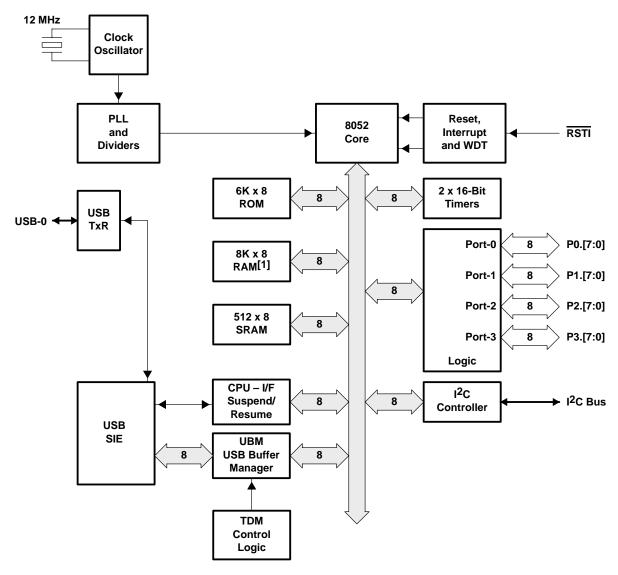
- Multiproduct support with one code and one chip (up to 16 products with one chip)
- Fully compliant with the USB release 1.1 specification
- Supports USB suspend/resume and remote wake-up operation
- Integrated 8052 Microcontroller with:
 - 256 × 8 RAM for internal data
 - 8k × 8 RAM code space available for downloadable firmware from host or I²C port. [1]
 - 512 × 8 shared RAM used for data buffers and endpoint descriptor blocks (EDB) [2]
 - Four 8052 GPIO ports, Port 0,1, 2 and 3
 - Master I²C controller for external slave device access
 - Watchdog timer
- Operates from a 12 MHz crystal
- On-chip PLL generates 48/12 MHz
- Supports a total of 4 input and 4 output endpoints
- Power-down mode
- Single 3.3 V operation [3]
- 64-pin TQFP package
- Applications include keyboard, bar code reader, flash memory reader, general-purpose controller

^[1] The TUSB3210 has 8K x 8 RAM for development.

^[2] This is the buffer space for USB packet transactions.

^{[3] 1.8} V required only to support suspend mode.

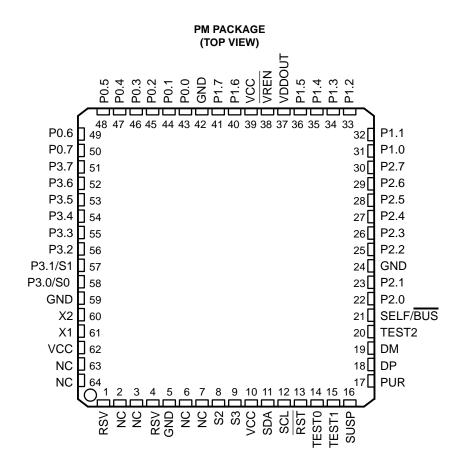
1.2 Functional Block Diagram



[1] The TUSB3210 has 8K x 8 RAM for development. 8k x 8 ROM version available. Contact TI Marketing

Figure 1-1. TUSB3210 Block Diagram

1.3 Terminal Assignments



1.4 Ordering Information

	PACKAGE
TA	PLASTIC QUAD FLATPACK (PM)
0°C to 70°C	TUSB3210PM

1.5 Terminal Functions

TERM	/INAL		PECCHIPTION
NAME	NO.	1/0	DESCRIPTION
DM	19	I/O	Differential data minus USB
DP	18	I/O	Differential data plus USB
GND	5,24,42,5 9	I	Power supply ground
NC	2, 3, 6, 7, 63, 64		No connection
P0.0	43	I/O	General-purpose I/O port 0 bit 0, Schmitt-trigger input 100 μA active pullup, open drain output
P0.1	44	I/O	General-purpose I/O port 0 bit 1, Schmitt-trigger input 100 μA active pullup, open drain output
P0.2	45	I/O	General-purpose I/O port 0 bit 2, Schmitt-trigger input 100 μA active pullup, open drain output
P0.3	46	I/O	General-purpose I/O port 0 bit 3, Schmitt-trigger input 100 μA active pullup, open drain output
P0.4	47	I/O	General-purpose I/O port 0 bit 4, Schmitt-trigger input 100 μA active pullup, open drain output
P0.5	48	I/O	General-purpose I/O port 0 bit 5, Schmitt-trigger input 100 μA active pullup, open drain output
P0.6	49	I/O	General-purpose I/O port 0 bit 6, Schmitt-trigger input 100 μA active pullup, open drain output
P0.7	50	I/O	General-purpose I/O port 0 bit 7, Schmitt-trigger input 100 μA active pullup, open drain output
P1.0	31	I/O	General-purpose I/O port 1 bit 0, Schmitt-trigger input 100 μA active pullup, open drain output
P1.1	32	I/O	General-purpose I/O port 1 bit 1, Schmitt-trigger input 100 μA active pullup, open drain output
P1.2	33	I/O	General-purpose I/O port 1 bit 2, Schmitt-trigger input 100 μA active pullup, open drain output
P1.3	34	I/O	General-purpose I/O port 1 bit 3, Schmitt-trigger input 100 μA active pullup, open drain output
P1.4	35	I/O	General-purpose I/O port 1 bit 4, Schmitt-trigger input 100 μA active pullup, open drain output
P1.5	36	I/O	General-purpose I/O port 1 bit 5, Schmitt-trigger input 100 μA active pullup, open drain output
P1.6	40	I/O	General-purpose I/O port 1 bit 6, Schmitt-trigger input 100 μA active pullup, open drain output
P1.7	41	I/O	General-purpose I/O port 1 bit 7, Schmitt-trigger input 100 μA active pullup, open drain output
P2.0	22	I/O	General-purpose I/O port 2 bit 0, Schmitt-trigger input 100 μA active pullup, open drain output
P2.1	23	I/O	General-purpose I/O port 2 bit 1, Schmitt-trigger input 100 μA active pullup, open drain output
P2.2	25	I/O	General-purpose I/O port 2 bit 2, Schmitt-trigger input 100 μA active pullup, open drain output
P2.3	26	I/O	General-purpose I/O port 2 bit 3, Schmitt-trigger input 100 μA active pullup, open drain output
P2.4	27	I/O	General-purpose I/O port 2 bit 4, Schmitt-trigger input 100 μA active pullup, open drain output
P2.5	28	I/O	General-purpose I/O port 2 bit 5, Schmitt-trigger input 100 μA active pullup, open drain output
P2.6	29	I/O	General-purpose I/O port 2 bit 6, Schmitt-trigger input 100 μA active pullup, open drain output
P2.7	30	I/O	General-purpose I/O port 2 bit 7, Schmitt-trigger input 100 μA active pullup, open drain output
P3.0/S0	58	I/O	General-purpose I/O port 3 bit 0, Schmitt-trigger input 100 μA active pullup, open drain output
P3.1/S1	57	I/O	General-purpose I/O port 3 bit 1, Schmitt-trigger input 100 μA active pullup, open drain output
P3.2	56	I/O	General-purpose I/O port 3 bit 2
P3.3	55	I/O	General-purpose I/O port 3 bit 3, Schmitt-trigger input 100 μA active pullup, open drain output; will not support INT1 input
P3.4	54	I/O	General-purpose I/O port 3 bit 4, Schmitt-trigger input 100 μA active pullup, open drain output
P3.5	53	I/O	General-purpose I/O port 3 bit 5, Schmitt-trigger input 100 μA active pullup, open drain output
P3.6	52	I/O	General-purpose I/O port 3 bit 6, Schmitt-trigger input 100 μA active pullup, open drain output
P3.7	51	I/O	General-purpose I/O port 3 bit 7, Schmitt-trigger input 100 μA active pullup, open drain output
PUR	17	0	Pullup resistor connection pin (3-state) push-pull CMOS output (±8 mA)
RST	13	I	Controller master reset signal, Schmitt-trigger input 100 µA active pullup
RSV	1, 4		Reserved (Do not connect these pins)
S2	8	I	VID/PID selection pin
S3	9	1	VID/PID selection pin

1.5 Terminal Functions (Continued)

TERM	RMINAL		DECORIDATION				
NAME	NO.	1/0	DESCRIPTION				
SCL	12	0	Serial clock I ² C; open drain output				
SDA	11	I/O	Serial data I ² C; open drain output				
SELF/BUS	21	I	USB power MODE select: self-powered (HIGH), bus-powered (LOW)				
SUSP	16	0	Suspend status signal: suspended (HIGH); unsuspended (LOW)				
TEST0	14	I	Test input0, Schmitt-trigger input 100 μA active pullup				
TEST1	15	I	Test input1, Schmitt-trigger input 100 μA active pullup				
TEST2	20	I	Test input2, Schmitt-trigger input 100 μA active pullup				
VCC	10,39,62	I	Power supply input 3.3 V typical				
VDDOUT	37	0	Power supply regulator output 1.8 V (May be used as an input when VREN is low)				
VREN	38	I	Voltage regulator enable: enable active LOW; disable active HIGH				
X1	61	I	12-MHz crystal input				
X2	60	0	12-MHz crystal output				

2 Functional Description

2.1 MCU Memory Map

Figure 2–1 illustrates the MCU memory map under boot and normal operation. It must be noted that the internal 256 bytes of IDATA are not shown since it is assumed to be in the standard 8052 location (0000 to 00FF). The shaded areas represent the internal ROM/RAM.

When SDW bit = 0 (Boot mode): The 6k-ROM is mapped to address (0000–17FF) and is duplicated in location (8000–97FF) in code space. The internal 8k-RAM is mapped to address range (0000–1FFF) in data space. Buffers, MMR and I/O are mapped to address range (FD80–FFFF) in data space.

When SDW bit = 1 (Normal mode): The 6k-ROM is mapped to (8000–97FF) in code space. The internal 8k-RAM is mapped to address range (0000–1FFF) code space. Buffers, MMR and I/O are mapped to address range (FD80–FFFF) in data space.

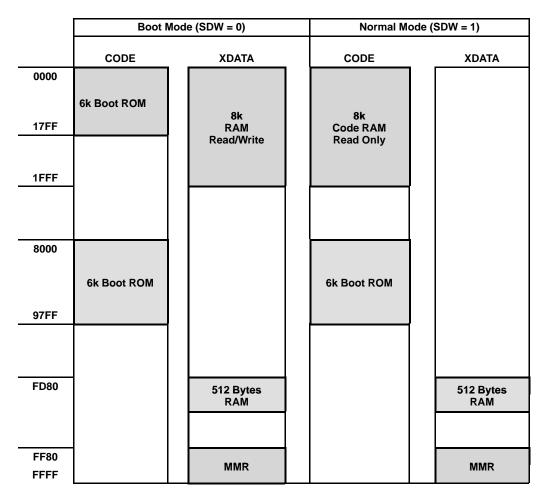


Figure 2-1. MCU Memory Map (TUSB3210)

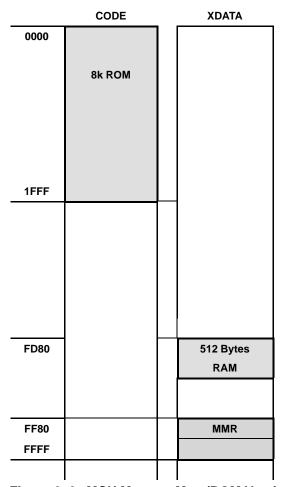


Figure 2-2. MCU Memory Map (ROM Version)

2.2 Miscellaneous Registers

2.2.1 TUSB3210 Boot Operation

Since the code-space is in RAM (with the exception of the boot ROM), the TUSB3210 firmware must be loaded from an external source. Two options for booting are available: an external serial EEPROM source connected to the I²C bus, or the host may be used via the USB. On device reset, the SDW bit (in ROM register) and CONT bit in USB Control Register (USBCTL) will be cleared. This will configure the memory space to boot mode (see memory map) and will keep the device *disconnected* from the host.

The first instruction will be fetched from location 0000 (which is in the 6k-ROM). The 8k-RAM will be mapped to XDATA space (location 0000h). MCU will execute a read from an external EEPROM and test to see if it contains the code (test for boot signature). If it contains the code, MCU will read from EEPROM and write to the 8k-RAM in XDATA space. If not, MCU will proceed to boot from USB.

Once the code is loaded, the MCU will set SDW to 1. This will switch the memory map to normal mode, i.e. the 8k-RAM will be mapped to code space, and the MCU will start executing from location 0000h. Once the switch is done, the MCU will set CONT to 1 (in USBCTL register) This will *connect* the device to the USB bus, resulting in the normal USB device enumeration.

2.2.2 MCNFG: MCU Configuration Register

This register is used to control the MCU clock rate.

7	6	5	4	3	2	1	0
12/48	XINT	RSV	R3	R2	R1	R0	SDW
R/W	R/W	R/O	R/O	R/O	R/O	R/O	R/W

BIT	NAME	RESET		FUNCTION				
0	SDW	0	This bit enal	his bit enables/disables boot ROM. In the ROM version of the controller, this bit has no effect.				
			SDW = 0	When clear, MCU executes from the 6k boot ROM space. The boot ROM appears in two locations: 0000 and 8000h. The 8k RAM is mapped to XDATA space; therefore, Read/Write operation is possible. This bit is set by MCU after the RAM load is completed. MCU cannot clear this bit. It is cleared on power-up-reset or function reset.				
			SDW = 1	When set by MCU, the 6k boot ROM maps to location 8000h, and the 8k RAM is mapped to code-space, starting at location 0000h. At this point, MCU executes from RAM, and write operation is disabled (No write operation is possible in code space).				
4–1	R[3:0]	No affect	These bits re	These bits reflect the device revision number				
5	RSV	0	Reserved	eserved				
6	XINT	0	XINT = 0 IN	NT1 source control bit. INT = 0 INT1 is connected to P3.3-pin and operates as a standard INT1 interrupt INT = 1 INT1 is connected to the OR of Port–2 inputs.				
7	12/48	0	This bit sele 12/48 = 0 1 12/48 = 1 4					

2.2.3 PUR_n: GPIO Pullup Register for Port n (n = 0 to 3)

7	6	5	4	3	2	1	0
Pin7	Pin6	Pin5	Pin4	Pin3	Pin2	Pin1	Pin0
R/W							

BIT	NAME	RESET	FUNCTION
0–7	PinN (N = 0 to 7)	0	The MCU may write to this register. If the MCU sets this bit to 1, the pullup resistor is disconnected from the pin. If the MCU clears this bit to 0, the pullup resistor is connected to the pin. The pullup resistor is connected to V _{CC} power supply.

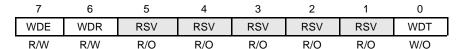
2.2.4 INTCFG: Interrupt Configuration

7	6	5	4	3	2	1	0
RSV	RSV	RSV	RSV	13	12	I1	10
R/O	R/O	R/O	R/O	R/W	R/W	R/W	R/W

BIT	NAME	RESET	FUNCTION
0–3	I[3:0]	0010	The MCU may write to this register to set the interrupt delay time for Port 2 on the MCU. The value of the lower nibble represents the delay in ms. Default after reset is 2 ms.
4–7	RSV	0	Reserved

2.2.5 WDCSR: Watchdog Timer, Control, and Status Register

A watchdog timer (WDT) with 1ms clock is provided. If this register is not accessed for a period of 32ms, the WDT counter will reset the MCU. (See Figure 2–3, Reset Diagram). When the IDL bit in PCON is set, the WDT will be suspended until an interrupt is detected. At this point, the IDL bit will be cleared and the WDT will resume operation.



BIT	NAME	RESET	FUNCTION					
0	WDT	0	period of 31	write a 1 to this bit to prevent the WDT from resetting the MCU. If MCU does not write a 1 in a ms, the WDT will reset the device. Writing a 0 has no effect on the WDT. (WDT is a 5-bit counter CLK). This bit is read as 0.				
5–1	RSV	0	Reserved =	Reserved = 0				
6	WDR	0	Watchdog retimer reset.	Watchdog reset indication bit. This bit indicates if the reset occurred due to power-on reset or watchdog timer reset.				
			WDR = 0	A power-up or USB reset occurred.				
			WDR = 1	A watchdog timeout reset occurred. To clear this bit, the MCU must write a 1. Writing a 0 has no effect.				
7	WDE	0	Watchdog T	imer Enable.				
			WDE = 0	This bit is cleared only on power-up, USB-reset (if enabled) or WDT reset.				
			WDE = 1	When MCU writes a 1 to this bit the WDT will start running. MCU cannot disable the WDT. Only power up or USB reset (if enabled) can clear it. When MCU is in idle state (IDL = 1), the WDT is suspended.				

2.2.6 PCON: Power Control Register (at SFR 87h)

7	6	5	4	3	2	1	0	
SMOD	RSV	RSV	RSV	GF1	GF0	RSV	IDL	
R/W	R/O	R/O	R/O	R/W	R/W	R/O	R/W	

BIT	NAME	RESET	FUNCTION				
0	IDL	0	MCU idle mode bit. This bit can be set by MCU and is cleared only by INT1 interrupt.				
			IDL = 0 MCU is NOT in idle mode. This bit is cleared by INT1 interrupt logic when INT1 is asserted for at least 400μs.				
			IDL = 1 MCU is in idle mode and RAM is in low-power mode. The oscillator/APLL is off and the WDT will be suspended. When in suspend mode, only INT1 can be used to exit from idle mode and generate an interrupt. INT1 must be asserted for at least 400μs for the interrupt to be recognized.				
1	RSV	0	Reserved				
3–2	GF[1:0]	00	General-purpose bits. MCU can write and read them.				
6–4	RSV	0	Reserved				
7	SMOD	0	Double baud rate control bit. For more information see UART serial interface in M8052 core specification.				

2.3 Buffers + I/O RAM Map

The address range from FD80 to FFFF is reserved for data buffers, setup packet, endpoint descriptor blocks (EDB), and all I/O. RAM space of 512 bytes [FD80–FF7F] is used for EDB and buffers. The FF80–FFFF range is used for memory mapped registers (MMR). Table 2–1 represents the internal XDATA space allocation.

Table 2-1. XDATA Space

DESCRIPTION	ADDRESS RANGE	
	FFFF	
Internal MMR (Memory mapped registers)	1	
	FF80	
	FF7F	
EDB (Endpoint descriptor blocks)	1	
	FF08	
	FF07	
Setup packet buffer	\uparrow	
	FF00	
	FEFF	512 byte
Input endpoint-0 buffer	↑ ====	RAM
	FEF8	
Outrot and a sist Obotton	FEF7 ↑	
Output endpoint-0 buffer	FEF0	
	FEEF	
Data buffers (367 bytes)	↑ <u></u> .	
	FD80	

Table 2–2. Memory Mapped Registers Summary (XDATA Range = FF80 \rightarrow FFFF)

ADDRESS	REGISTER	DESCRIPTION
FFFF	FUNADR	FUNADR: Function address register
FFFE	USBSTA	USBSTA: USB status register
FFFD	USBMSK	USBMSK: USB interrupt mask register
FFFC	USBCTL	USBCTL: USB control register
1	RESERVED	
FFF6	VIDSTA	VIDSTA: VID/PID status register
1	RESERVED	
FFF3	I2CADR	I2CADR: I2C address register
FFF2	I2CDAI	I2CDAI: I2C data-input register
FFF1	I2CDAO	I2CDAO: I2C data-output register
FFF0	I2CSTA	I2CSTA: I2C status and control register
1	RESERVED	
FF97	PUR3	Port 3 pullup resistor register
FF96	PUR2	Port 2 pullup resistor register
FF95	PUR1	Port 1 pullup resistor register
FF94	PUR0	Port 0 pullup resistor register
FF93	WDCSR	WDCSR: Watchdog timer, control & status register
FF92	VECINT	VECINT: Vector interrupt register

Table 2–2. Memory Mapped Registers Summary (XDATA Range = FF80 \rightarrow FFF) (Continued)

ADDRESS	REGISTER	DESCRIPTION				
FF91	RESERVED					
FF90	MCNFG	MCNFG: MCU configuration register				
\uparrow	RESERVED					
FF84	INTCFG	INTCFG: Interrupt delay configuration register				
FF83	OEPBCNT_0	OEPBCNT_0: Output endpoint-0 byte count register				
FF82	OEPCNFG_0	OEPCNFG_0: Output endpoint-0 configuration register				
FF81	IEPBCNT_0	IEPBCNT_0: Input endpoint-0 byte count register				
FF80	IEPCNFG_0	IEPCNFG_0: Input endpoint-0 configuration register				

Table 2-3. EDB and Buffer Allocations in XDATA

ADDRESS		DESCRIPTION				
FF7F						
1	(32-bytes)	RESERVED				
FF60						
FF5F						
1	(8-bytes)	Input endpoint_3: configuration				
FF58						
FF57						
↑	(8-bytes)	Input endpoint_2: configuration				
FF50						
FF4F						
1	(8-bytes)	Input endpoint_1: configuration				
FF48						
FF47						
↑	(40-bytes)	RESERVED				
FF20						
FF1F						
\uparrow	(8-bytes)	Output endpoint_3: configuration				
FF18		= 5				
FF17						
1	(8-bytes)	Output endpoint_2: configuration				
FF10						
FF0F						
1	(8-bytes)	Output endpoint_1: configuration				
FF08						
FF07						
1	(8-bytes)	Setup packet block				
FF00						
FEFF						
1	(8-bytes)	Input endpoint_0 buffer				
FEF8						

Table 2–3. EDB and Buffer Allocations in XDATA (Continued)

ADDRESS		DESCRIPTION
FEF7		
1	(8-bytes)	Output endpoint_0 buffer
FEF0		
FEEF	TOPBUFF	Top of buffer space
\uparrow		
1		Buffers space
1		
FD80	STABUFF	Start of buffer space

2.4 Endpoint Descriptor Block (EDB-1 to EDB-3)

Data transfers between USB, MCU and external devices are defined by an endpoint descriptor block (EDB). Four input and four output EDBs are provided. With the exception of EDB–0 (I/O Endpoint–0), all EDBs are located in SRAM as shown in Table 2–3. Each EDB contains information describing the X and Y buffers. In addition, it provides general status information.

Table 2–4 illustrates the EDB entries for EDB–1 to EDB–3. EDB–0 registers will be described separately.

Table 2–4. EDB Entries in RAM (n = 1 to 3)

Offset	ENTRY NAME	DESCRIPTION
07	EPSIZXY_n	I/O endpoint_n: X/Y buffer size
06	EPBCTY_n	I/O endpoint_n: Y byte count
05	EPBBAY_n	I/O endpoint_n: Y buffer base address
04	SPARE	Not used
03	SPARE	Not used
02	EPBCTX_n	I/O endpoint_n: X byte count
01	EPBBAX_n	I/O endpoint_n: X buffer base address
00	EPCNF_n	I/O endpoint_n: configuration

2.4.1 OEPCNF_n: Output Endpoint Configuration (n=1 to 3)

7	6	5	4	3	2	1	0
UBME	ISO	TOGLE	DBUF	STALL	USBIE	RSV	RSV
R/W	R/W	R/W	R/W	R/W	R/W	R/O	R/O

BIT	NAME	RESET		FUNCTION					
1–0	RSV	0	Reserved						
2	USBIE	х	USBIE = 0	s interrupt enable on transaction completion. Set/clear by MCU. BIE = 0 no interrupt BIE = 1 interrupt on transaction completion					
3	STALL	0	USB stall co	SB stall condition indication. Set/clear by MCU.					
			STALL = 0	TALL = 0 No stall					
			STALL = 1	STALL = 1 USB stall condition. If set by MCU, a STALL handshake is initiated and the bit is cleared by MC					
4	DBUF	Х	Double buffer enable. Set/clear by MCU.						
			DBUF = 0	Primary buffer only (X-buffer only)					
			DBUF = 1	Toggle bit selects buffer					
5	TOGLE	Х	USB Toggle	bit. This bit reflects the toggle sequence bit of DATA0, DATA1					
6	ISO	х	ISO = 0	Non-isochronous transfer. This bit must be cleared by MCU since only Non-isochronous transfer is supported.					
7	UBME	х	UBME = 0 L	UBM enable/disable bit. Set/clear by MCU. UBME = 0 UBM cannot use this endpoint. UBME = 1 UBM can use this endpoint.					

2.4.2 OEPBBAX_n: Output Endpoint X-Buffer Base-Address (n=1 to 3)

7	6	5	4	3	2	1	0
A ₁₀	A ₉	A ₈	A ₇	A ₆	A ₅	A ₄	A ₃
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

BIT	NAME	RESET	FUNCTION
7–0	A[10:3]		A[10:3] of X-buffer base address (padded with 3-LSB of zeros for a total of 11-bits). This value is set by the MCU. UBM or DMA uses this value as the start-address of a given transaction. Furthermore, UBM or DMA does not change this value at the end of a transaction.

2.4.3 OEPBCTX_n: Output Endpoint X Byte Count (n=1 to 3)

7	6	5	4	3	2	1	0
NAK	C ₆	C ₅	C ₄	C ₃	C ₂	C ₁	C ₀
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

BIT	NAME	RESET	FUNCTION
6-0	C[6:0]	X Suffer Byte count: X000.0000b > Count = 0 X000.0001b > Count = 1 byte : : X011.1111b > Count = 63 bytes X100.0000b > Count = 64 bytes Any value ≥ 100.0001b produces unpredictable results. X NAK= 0 No valid data in buffer. Ready for host out NAK= 1 Buffer contains a valid packet from Host (host-out request is NAK)	
7	NAK	х	1

2.4.4 OEPBBAY_n: Output Endpoint Y-Buffer Base-Address (n=1 to 3)

7	6	5	4	3	2	1	0
A ₁₀	Ag	A ₈	A ₇	A ₆	A ₅	A ₄	А3
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

BIT	NAME	RESET	FUNCTION
7–0	A[10:3]		A[10:3] of Y-buffer base address (padded with 3-LSB of zeros for a total of 11 bits). This value is set by the MCU. UBM or DMA uses this value as the start-address of a given transaction. Furthermore, UBM or DMA does not change this value at the end of a transaction.

2.4.5 OEPBCTY_n: Output Endpoint Y Byte Count (n=1 to 3)

7	6	5	4	3	2	1	0
NAK	C ₆	C ₅	C ₄	C ₃	C ₂	C ₁	C ₀
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

BIT	NAME	RESET	FUNCTION
6-0	C[6:0]	x	Y-Byte count: X000.0000b > Count = 0 X000.0001b > Count = 1 byte : : : X011.1111b > Count = 63 bytes X100.0000b > Count = 64 bytes Any value ≥ 100.0001b will result in unpredictable results.
7	NAK	Х	NAK= 0 No valid data in buffer. Ready for host out NAK= 1 Buffer contains a valid packet from host (host-out request is NAK)

2.4.6 OEPSIZXY_n: Output Endpoint X/Y Byte Count (n=1 to 3)

7	6	5	4	3	2	1	0
RSV	S ₆	S ₅	S ₄	S ₃	S ₂	S ₁	S ₀
R/O	R/W						

BIT	NAME	RESET	FUNCTION
6–0	S[6:0]	x	X AND Y-Buffer size: 0000.0000b > Count = 0 0000.0001b > Count = 1 byte : : 0011.1111b > Count = 63 bytes 0100.0000b > Count = 64 bytes Any value ≥ 100.0001b produces unpredictable results.
7	RSV	0	Reserved

2.4.7 IEPCNF_n: Input Endpoint Configuration (n=1 to 3)

7	6	5	4	3	2	1	0
UBME	ISO	TOGLE	DBUF	STALL	USBIE	RSV	RSV
R/W	R/W	R/W	R/W	R/W	R/W	R/O	R/O

BIT	NAME	RESET		FUNCTION				
1–0	RSV	Х	Reserved =	0				
2	USBIE	х	USBIE = 0	JSB interrupt enable on transaction completion. JSBIE = 0 No interrupt JSBIE = 1 Interrupt on transaction completion				
3	STALL	0	USB stall co	ondition indication. Set by UBM, but can be set/cleared by MCU.				
			STALL = 0	No stall				
			STALL = 1	USB stall condition. If set by MCU, a STALL handshake will be initiated and the bit is cleared automaticallly.				
4	DBUF	х	Double buffe	er enable				
			DBUF = 0	Primary buffer only (X-buffer only)				
			DBUF = 1	Toggle bit selects buffer				
5	TOGLE	Х	USB Toggle	bit. This bit reflects the toggle sequence bit of DATA0, DATA1				
6	ISO	х	ISO = 0	Non-isochronous transfer. This bit must be cleared by MCU since only Non-isochronous transfer is supported.				
7	UBME	х	UBME = 0 U	JBM can use this endpoint. JBM can use this endpoint.				

2.4.8 IEPBBAX_n: Input Endpoint X-Buffer Base-Address (n=1 to 3)

7	6	5	4	3	2	1	0	
A ₁₀	A ₉	A ₈	A ₇	A ₆	A ₅	A ₄	Аз	l
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	

ĺ	BIT	NAME	RESET	FUNCTION
	7–0	A[10:3]	х	A[10:3] of X-buffer base address (padded with 3-LSB of zeros for a total of 11 bits). This value is set by the MCU. UBM or DMA uses this value as the start-address of a given transaction. Furthermore, UBM or DMA does not change this value at the end of a transaction.

2.4.9 IEPBCTX_n: Input Endpoint X-Byte Base-Address (n=1 to 3)

7	6	5	4	3	2	1	0
NAK	C ₆	C ₅	C ₄	C ₃	C ₂	C ₁	C ₀
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

BIT	NAME	RESET	FUNCTION
6–0	C[6:0]	x	X-Buffer Byte count: X000.0000b > Count = 0 X000.0001b > Count = 1 byte : : : X011.1111b > Count = 63 bytes X100.0000b > Count = 64 bytes Any value ≥ 100.0001b produces unpredictable results.
7	NAK	х	NAK = 0 Buffer contains a valid packet for host-in transaction NAK = 1 Buffer is empty (host-in request is NAK)

2.4.10 IEPBBAY_n: Input Endpoint Y-Buffer Base-Address (n=1 to 3)

7	6	5	4	3	2	1	0	
A ₁₀	Ag	A ₈	A ₇	A ₆	A ₅	A ₄	A ₃]
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	-

BIT	NAME	RESET	FUNCTION
7–0	A[10:3]		A[10:3] of Y-buffer base address (padded with 3-LSB of zeros for a total of 11 bits). This value is set by the MCU. UBM or DMA uses this value as the start-address of a given transaction. Furthermore, UBM or DMA does not change this value at the end of a transaction.

2.4.11 IEPBCTY_n: Input Endpoint Y Byte Count (n=1 to 3)

	7	6	5	4	3	2	1	0
	NAK	C ₆	C ₅	C ₄	C ₃	C ₂	C ₁	C ₀
,	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

BIT	NAME	RESET	FUNCTION
6–0	C[6:0]	х	X-Byte count: X000.0000b > Count = 0 X000.0001b > Count = 1 byte : : : : : : : : : : : : : : : : : :
7	NAK	Х	NAK = 0 Buffer contains a valid packet for host-in transaction NAK = 1 Buffer is empty (host-in request is NAK)

2.4.12 IEPSIZXY_n: Input Endpoint X/Y-Buffer Size (n=1 to 3)

7	6	5	4	3	2	1	0
RSV	S ₆	S ₅	S ₄	S ₃	S ₂	S ₁	S ₀
R/O	R/W						

BIT	NAME	RESET	FUNCTION
6–0	S[6:0]	х	X AND Y-Buffer size: 0000.0000b > Count = 0 0000.0001b > Count = 1 byte : : 0011.1111b > Count = 63 bytes 0100.0000b > Count = 64 bytes Any value ≥ 100.0001b produces unpredictable results.
7	RSV	х	Reserved

2.5 Endpoint-0 Descriptor Registers

Unlike EDB-1 to EDB-3, which are defined as memory entries in SRAM, Endpoint-0 is described by a set of 4 registers (two for output and two for input). Table 2–5 defines the registers and their respective addresses used for EDB-0 description. EDB-0 has no *Base-Address-Register*, since these addresses are hardwired to FEF8 and FEF0. Note that the bit positions have been preserved to provide consistency with EDB-n (n = 1 to 3).

Table 2-5. Input/Output EDB-0 Registers

ADDRESS	REGISTER NAME	DESCRIPTION	BASE ADDRESS
FF83	OEPBCNT_0	Output endpoint_0: byte count register	
FF82	OEPCNFG_0	Output endpoint_0: configuration register	FEF0
FF81	IEPBCNT_0	Input endpoint_0: byte count register	
FF80	IEPCNFG_0	Input endpoint_0: configuration register	FEF8

2.5.1 IEPCNFG_0: Input Endpoint-0 Configuration Register

7	6	5	4	3	2	1	0
UBME	RSV	TOGLE	RSV	STALL	USBIE	RSV	RSV
R/W	R/O	R/O	R/O	R/W	R/W	R/O	R/O

BIT	NAME	RESET		FUNCTION		
1–0	RSV	0	Reserved			
2	USBIE	0	USBIE = 0	JSB interrupt enable on transaction completion. Set/clear by MCU JSBIE = 0 No interrupt JSBIE = 1 Interrupt on transaction completion		
3	STALL	0	USB stall co	ondition indication. Set/clear by MCU.		
			STALL = 0	No stall		
			STALL = 1	USB stall condition. If set by MCU, a STALL handshake is initiated and the bit is cleared automatically by next setup transaction.		
4	RSV	0	Reserved			
5	TOGLE	0	USB toggle	bit. This bit reflects the toggle sequence bit of DATA0, DATA1		
6	RSV	0	Reserved			
7	UBME	0	UBME = 0 U	e/disable bit. Set/clear by MCU. JBM cannot use this endpoint. JBM can use this endpoint.		

2.5.2 IEPBCNT_0: Input Endpoint-0 Byte Count Register

7	6	5	4	3	2	1	0
NAK	RSV	RSV	RSV	C ₃	C ₂	C ₁	C ₀
R/W	R/O	R/O	R/O	R/W	R/W	R/W	R/W

BIT	NAME	RESET	FUNCTION
3–0	C[3:0]	0000	Byte count: 0000b > Count = 0 : : 0111b > Count = 7 1000b > Count = 8 1001b to 1111b are reserved. (If used, defaults to 8)
6–4	RSV	0	Reserved
7	NAK	1	NAK= 0 Buffer contains a valid packet for host-in transaction NAK= 1 Buffer is empty (host-in request is NAK)

2.5.3 OEPCNFG_0: Output Endpoint-0 Configuration Register

	7	6	5	4	3	2	1	0
	UBME	RSV	TOGLE	RSV	STALL	USBIE	RSV	RSV
,	R/W	R/O	R/O	R/O	R/W	R/W	R/O	R/O

BIT	NAME	RESET		FUNCTION			
1–0	RSV	0	Reserved	Reserved			
2	USBIE	0	USBIE = 0	USB interrupt enable on transaction completion. Set/clear by MCU USBIE = 0 no interrupt USBIE = 1 interrupt on transaction completion			
3	STALL	0	USB stall co	USB stall condition indication. Set/clear by MCU.			
			STALL = 0 No stall				
			STALL = 1	USB stall condition. If set by MCU, a STALL handshake is initiated and the bit is cleared automaticallly.			
4	RSV	0	Reserved				
5	TOGLE	0	USB toggle	bit. This bit reflects the toggle sequence bit of DATA0, DATA1			
6	RSV	0	Reserved				
7	UBME	0	UBME = 0 U	e/disable bit. Set/clear by MCU. JBM cannot use this endpoint. JBM can use this endpoint.			

2.5.4 OEPBCNT_0: Output Endpoint-0 Byte Count Register

	7	6	5	4	3	2	1	0
	NAK	RSV	RSV	RSV	C ₃	C ₂	C ₁	C ₀
,	R/W	R/O	R/O	R/O	R/W	R/W	R/W	R/W

BIT	NAME	RESET	FUNCTION
3–0	C[3:0]	0000	Byte count: 0000b > Count = 0 : : 0111b > Count = 7 1000b > Count = 8 1001b to 1111b are reserved. (If used, defaults to 8)
6–4	RSV	0	Reserved = 0
7	NAK	1	NAK= 0 No valid data in buffer. Ready for host out NAK= 1 Buffer contains a valid packet from host. (NAK the host)

2.6 USB Registers

2.6.1 FUNADR: Function Address Register

This register contains the device function address.

7	6	5	4	3	2	1	0
RSV	FA6	FA5	FA4	FA3	FA2	FA1	FA0
R/O	R/W						

BIT	NAME	RESET	FUNCTION
6–0	FA[6:0]	0000000	These bits define the current device address assigned to the function. MCU writes a value to this register as a result of SET-ADDRESS host command.
7	RSV	0	Reserved

2.6.2 USBSTA: USB Status Register

All bits in this register are set by the hardware and will be cleared by MCU when writing a 1 to the proper bit location (writing a 0 has no effect). In addition, each bit can generate an interrupt if its corresponding mask bit is set (R/C notation indicates read and clear only by MCU).

	7	6	5	4	3	2	1	0
RS	STR	SUSR	RESR	PWOFF	PWON	SETUP	RSV	STPOW
R	/C	R/C	R/C	R/C	R/C	R/C	R/O	R/C

BIT	NAME	RESET		FUNCTION		
0	STPOW	0	SETUP overw setup buffer.	rite bit. Set by hardware when setup packet is received while there is already a packet in the		
			STPOW = 0	MCU can clear this bit by writing a 1. (Writing 0 has no effect)		
			STPOW = 1	SETUP overwrite		
1	RSV	0	Reserved			
2	SETUP	0		SETUP transaction received bit. As long as SETUP is 1, IN and OUT on endpoint-0 is NAK regardless of the value of their real NAK bits		
			SETUP = 0	MCU can clear this bit by writing a 1. (Writing 0 has no effect)		
			SETUP = 1	SETUP transaction received.		
3	PWON	0	Power on request for Port-3. This bit indicates if power-on to Port-3 has been received. This bit generates a PWON interru			
			PWON = 0	MCU can clear this bit by writing a 1. (Writing 0 has no effect)		
			PWON = 1	Power on to Port-3 has been received.		
4	PWOFF	0		uest for Port-3. This bit indicates whether power-off to Port-3 has been received. This bit WOFF interrupt (If enabled).		
			PWOFF = 0	MCU can clear this bit by writing a 1. (Writing 0 has no effect)		
			PWOFF = 1	Power off to Port-3 has been received		
5	RESR	0	Function resur	me request bit		
			RESR = 0	MCU can clear this bit by writing a 1. (Writing 0 has no effect)		
			RESR = 1	Function resume is detected		
6	SUSR	0	Function suspended request bit. This bit is set in response to a global or selective suspend condition. SUSR =0 MCU can clear this bit by writing a 1. (Writing 0 has no effect) SUSR =1 Function suspend is detected.			
7	RSTR	0	USB function (RSTR = 0 MC	Function reset request bit. This bit is set in response to host initiating a port reset. This bit is not affected by USB function reset. RSTR = 0 MCU can clear this bit by writing a 1. (Writing 0 has no effect) RSTR = 1 Function reset is detected.		

2.6.3 USBMSK: USB Interrupt Mask Register

7	6	5	4	3	2	1	0
RSTR	SUSR	RESR	PWOFF	PWON	SETUP	RSV	STPOW
R/W	R/W	R/W	R/W	R/W	R/W	R/O	R/W

BIT	NAME	RESET	FUNCTION
0	STPOW	0	SETUP overwrite interrupt enable bit STPOW = 0 STPOW interrupt disabled STPOW = 1 STPOW interrupt enabled
1	RSV	0	Reserved = 0
2	SETUP	0	SETUP interrupt enable bit SETUP = 0 SETUP interrupt disabled SETUP = 1 SETUP interrupt enabled
3	PWON	0	Power-on interrupt enable bit PWON = 0 PWON interrupt disabled PWON = 1 PWON interrupt enabled
4	PWOFF	0	Power-off interrupt enable bit PWOFF = 0 PWOFF interrupt disabled PWON = 1 PWOFF interrupt enabled
5	RESR = 0 function resu		Function resume interrupt enable RESR = 0 function resume interrupt disabled RESR = 1 function resume interrupt enabled
		0	Function suspend interrupt enable SUSR = 0 function suspend interrupt disabled SUSR = 1 function suspend interrupt enabled
7	RSTR 0 Function reset interrupt enable RSTR = 0 function reset interrup		Function reset interrupt enable RSTR = 0 function reset interrupt disabled RSTR = 1 function reset interrupt enabled

2.6.4 USBCTL: USB Control Register

Unlike the other registers, this register is cleared by the power-up-reset signal only. The USB-reset cannot reset this register. (See Figure 2–3: Reset Diagram)

7	6	5	4	3	2	1	0
CONT	RSV	RWUP	FRSTE	RWE	B/S	SIR	DIR
R/W	R/O	R/W	R/W	R/W	R/W	R/W	R/W

BIT	NAME	RESET		FUNCTION				
0	DIR	0	transfer dire	As a response to a setup packet, the MCU will decode the request and set or clear this bit to reflect the data transfer direction. DIR = 0 > USB data OUT transaction. (From host to TUSB3210) DIR = 1 > USB data IN transaction. (From TUSB3210 to host)				
1	SIR	0		errupt status bit. This bit is controlled by the MCU to indicate to the hardware when SETUP being served.				
			SIR = 0	SETUP interrupt is not served. MCU will clear this bit before exiting the SETUP interrupt routine.				
			SIR = 1	SETUP interrupt is in progress. MCU will set this bit when servicing the SETUP interrupt.				
2	B/S	0	B/S = 0 > T	wer control bit he device is bus-powered he device is self-powered				
3	RWE	0	Remote wa	ke-up enable bit.				
			RWE = 0	MCU clears it when host sends command to clear the feature.				
			RWE = 1	MCU writes 1 to it when host sends set device feature command to enable remote wake-up feature				
4	FRSTE	1	FRSTE = 0	set connection bit. This bit connects/disconnects the USB function reset from the MCU reset. function reset is not connected to MCU reset function reset is connected to MCU reset				
5	RWUP	0	Device rem	ote wake-up request. This bit is set by MCU and is cleared automatically.				
			RWUP = 0	Writing a 0 to this bit has no effect.				
			RWUP = 1	When MCU writes a 1, a Remote wake-up pulse is generated.				
6	RSV	0	Reserved					
7	CONT	0	CONT = 0 l	sconnect Bit Jpstream port is disconnected. Pullup disabled Jpstream port is connected. Pullup enabled				

2.6.5 VIDSTA: VID/PID Status Register

This register is used to read the value on four external pins. The firmware can use this value to select one of the vendor identification/product identifications (VID/PID) stored in memory. The TUSB3210/D supports up to 16 unique VID/PIDs with application code to support different products. This provides a unique opportunity for original equipment manufacturers (OEM) to have one device ROM programmed to support up to 16 different product lines by using S0–S3 to select VID/PID and behavioral application code for the selected product.

7	6	5	4	3	2	1	0
RSV	RSV	RSV	RSV	S3	S2	S1	S0
R/O							

BIT	NAME	RESET	FUNCTION				
3–0	S[3:0] x VID/PID selection bits. These bits reflect the status of the external pins as defined by Table 2–7. pin tied Low will be reflected as 0 and a pin tied high will be reflected as a 1.						
7–4	RSV	0	Reserved = 0				

Table 2-6. External Pins Mapping to S[3:0] in VIDSTA Register

	PIN	VIDSTA REGISTER	COMMENTO
NO.	NAME	S[3:0]	COMMENTS
58	P3.0	S0	Dual function P3.0 I/O or S0 input
57	P3.1	S1	Dual function P3.1 I/O or S1 input
8	S2	S2	S2-pin is input
9	S3	S3	S3-pin is input

2.7 Function Reset and Power-Up Reset Interconnect

Figure 2–3 represents the logical connection of USB-function-reset ($\overline{\text{USBR}}$) and power-up-reset ($\overline{\text{RST}}$ -pin). The internal $\overline{\text{RESET}}$ signal is generated from the $\overline{\text{RST}}$ pin ($\overline{\text{PURS}}$ signal) or from the USB-reset ($\overline{\text{USBR}}$ signal). The $\overline{\text{USBR}}$ can be enabled or disabled by the FRSTE bit in the USBCTL register (on power up FRSTE is = 0). The internal $\overline{\text{RESET}}$ is used to reset all registers and logic, with the exception of the USBCTL and MISCTL registers. The USBCTL and MCU configuration register (MCNFG) are cleared by $\overline{\text{PURS}}$ signal only.

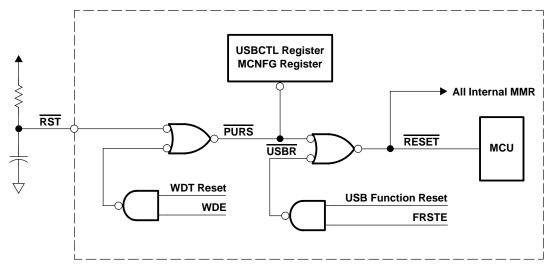


Figure 2-3. Reset Diagram

2.8 Pullup Resistor Connect/Disconnect

After reading firmware into RAM the TUSB3210 can re-enumerate using the new firmware (no need to physically disconnect and re-connect the cable). Figure 2–4 shows an equivalent circuit implementation for *Connect* and *Disconnect* from a USB up-stream port (also see Firgure 4–4b). When CONT bit in USBCTL register is 1, the CMOS driver sources VDD to the pullup resistor (PUR pin) presenting a normal connect condition to the USB hub (high speed). When CONT bit is 0, PUR pin is driven low. In this state, the 1.5 k Ω resistor is connected to GND, resulting in device *disconnection* state. The PUR driver is a CMOS driver that can provide (VDD–0.1) volt minimum at 8 mA source current.

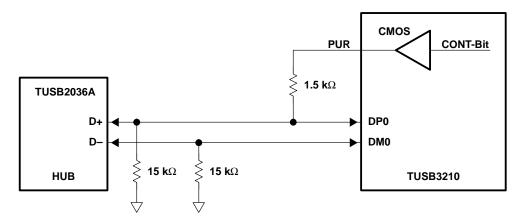


Figure 2-4. Pullup Resistor Connect/Disconnect Circuit

2.9 8052 Interrupt and Status Registers

All 8052 standard 5 interrupt sources are preserved. SIE is the standard interrupt enable register, which controls the five interrupt sources. All the additional interrupt sources are connected together as an OR to generate EX0. XINTO# signal is provided to interrupt an external MCU (see Interrupt connection diagram, Figure 2–5).

INTERRUPT SOURCE	DESCRIPTION	START ADDRESS	COMMENTS
ES	UART interrupt	0023H	
ET1	Timer–1 interrupt	001BH	
EX1	Internal INT1	0013H	Used for P2[7:0] interrupt
ET0	Timer–0 interrupt	000BH	
EX0	Internal INT0	0003H	Used for all internal peripherals
Reset		H0000	

Table 2-7. 8052 Interrupt Location Map

2.9.1 8052 Standard Interrupt Enable Register

7	6	5	4	3	2	1	0
EA	RSV	RSV	ES	ET1	EX1	ET0	EX0
R/W	R/O	R/O	R/W	R/W	R/W	R/W	R/W

BIT	NAME	RESET	FUNCTION
0	EX0	0	Enable or disable external interrupt-0 EX0 = 0 external interrupt-0 is disabled EX0 = 1 external interrupt-0 is enabled
1	ET0	0	Enable or disable timer-0 interrupt ET0 = 0 timer-0 interrupt is disabled ET0 = 1 timer-0 interrupt is enabled
2	EX1	0	Enable or disable external interrupt-1 EX1 = 0 external interrupt-1 is disabled EX1 = 1 external interrupt-1 is enabled
3	ET1	0	Enable or disable timer-1 interrupt ET1 = 0 timer-1 interrupt is disabled ET1 = 1 timer-1 interrupt is enabled
4	ES	0	Enable or disable serial port interrupts ES = 0 serial port interrupt is disabled ES = 1 serial port interrupt is enabled
5,6	RSV	0	Reserved
7	EA	0	Enable or disable all interrupts (global disable) EA = 0 disable all interrupts EA = 1 each interrupt source is individually controlled.

2.9.2 Additional Interrupt Sources

All nonstandard 8052 interrupts (USB, I²C, etc.) are connected as an OR to generate an internal INT0. It must be noted that the external INT0 and INT1 are not used. Furthermore, INT0 must be programmed as an active low level interrupt (not edge triggered). A vector interrupt register is provided to identify all interrupt sources (see vector interrupt register definition). Up to 64 interrupt vectors are provided. It is the responsibility of the MCU to read the vector and dispatch the proper interrupt routine.

2.9.3 VECINT: Vector Interrupt Register

This register contains a vector value identifying the internal interrupt source that trapped to location 0003H. Writing any value to this register removes the vector and update the next vector value (if another interrupt is pending). Note that the vector value is offset. Therefore, its value is in increments of two (bit-0 is set to 0). When no interrupt is pending, the vector is set to 00h. (see Table 2–8: Vector Interrupt Values). As shown, the interrupt vector is divided into two fields; I[2:0] and G[3:0]. The I-field defines the interrupt source within a group (on first come first served basis) and the G-field, which defines the group number. Group G0 is the lowest and G15 is the highest priority.

7	6	5	4	3	2	1	0
G3	G2	G1	G0	12	I1	10	0
R/W	R/O						

BIT	NAME	RESET	FUNCTION
3–1	I[2:0]	000	This field defines the interrupt source in a given group. See Table 2–8: Vector Interrupt Values. Bit-0 is always = 0, therefore, vector values will be offset by two.
7–4	G[3:0]	0000	This field defines the interrupt group. I[2:0] and G[3:0] combine to produce the actual interrupt vector.

Table 2-8. Vector Interrupt Values

G[3:0] (Hex)	I[2:0] (Hex)	VECTOR (Hex)	INTERRUPT SOURCE		
0	0	00	No interrupt		
1	0	10	NOT USED		
1	1	12	Output endpoint-1		
1	2	14	Output endpoint-2		
1	3	16	Output endpoint-3		
1	4–7	18–1E	NOT USED		
2	0	20	NOT USED		
2	1	22	Input endpoint-1		
2	2	24	Input endpoint-2		
2	3	26	Input endpoint-3		
2	4–7	28–2E	NOT USED		
3	0	30	STPOW packet received		
3	1	32	SETUP packet received		
3	2	34	PWON interrupt		
3	3	36	PWOFF interrupt		
3	4	38	RESR interrupt		
3	5	3A	SUSR interrupt		
3	6	3C	RSTR interrupt		
3	7	3E	RESERVED		
4	0	40	I2C TXE interrupt		
4	1	42	I2C RXF interrupt		
4	2	44	Input endpoint-0		
4	3	46	Output endpoint-0		
4	4–7	48 → 4E	NOT USED		
5–15	Х	90 → FE	NOT USED		

2.9.4 Logical Interrupt Connection Diagram (INTO)

Figure 2–5 represents the logical connection of the interrupt sources and its relation with XINTO#. The priority encoder generates an 8-bit vector, corresponding to 64 interrupt sources (not all are used). The interrupt priorities are hard wired. Vector 4E is the highest and 00 is the lowest.

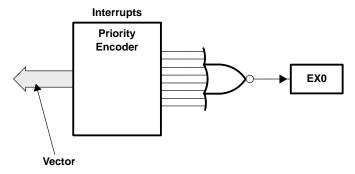


Figure 2-5. Internal Vector Interrupt (EX0)

2.9.5 P2[7:0] Interrupt (INT1)

Figure 2–6 illustrates the conceptual Port-2 interrupt. All Port-2 input signals are connected in a logical OR to generate INT1 interrupt. Note that the inputs are active low and INT1 is programed as an edge-triggered interrupt. In addition, INT1 is connected to the suspend/resume logic for remote wake-up support. As illustrated, XINT-bit in MCU configuration register (MCNFG) is used to select the EXI interrupt source. When XINT = 0, P3.3 is the source, and when XINT = 1, P2[7:0] is the source.

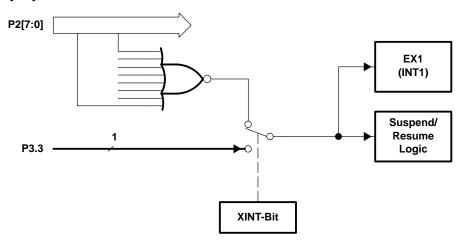


Figure 2-6. P2[7:0] Input Port Interrupt Generation

2.10 I2C Registers

2.10.1 I2CSTA: I2C Status and Control Register

This register is used to control the stop condition for read and write operation. In addition, it provides transmitter and receiver handshake signals with their respective interrupt enable bits.

7	6	5	4	3	2	1	0
RXF	RIE	ERR	1/4	TXE	TIE	SRD	SWR
R/C	R/W	R/C	R/W	R/C	R/W	R/W	R/W

BIT	NAME	RESET		FUNCTION			
0	SWR	0		condition. This bit defines if the I2C controller generates a stop condition when data from I2CDAO transmitted to an external device.			
			SWR = 0	Stop condition is not generated when data from I2CDAO register is shifted out to an external device.			
			SWR = 1	Stop condition is generated when data from I2CDAO register is shifted out to an external device.			
1	SRD	0		op read condition. This bit defines if the I2C controller will generate a stop condition when data is received d loaded into I2CDAI register.			
			SRD = 0	D = 0 Stop condition is not generated when data from SDA line is shifted into I2CDAI register.			
			SRD = 1	1 1			
2	TIE	0	TIE = 0 In	nitter empty interrupt enable. terrupt disable terrupt enable			
3	TXE	1		² C transmitter empty. This bit indicates that data can be written to the transmitter. It can be used for polling or can generate an interrupt.			
			TXE = 0	E = 0 Transmitter is full. This bit is cleared when MCU writes a byte to I2CDAO register.			
			TXE = 1	Transmitter is empty. The I2C controller sets this bit when the content of I2CDAO register is copied to the SDA shift–register.			
4	1/4	0		selection. 00 kHz bus speed 00 kHz bus speed			
5	ERR	0	MCU. ERR = 0	condition. This bit is set by the hardware when the device does not respond. It is cleared by the No bus error Bus error condition has been detected. Clears when MCU writes a 1. Writing a 0 has no effect.			
6	RIE	0	RIE = 0 In	I ² C receiver ready interrupt enable. RIE = 0 Interrupt disable RIE = 1 Interrupt enable			
7	RXF	0		I ² C receiver full. This bit indicates that the receiver contains new data. It can be used for polling or it can generate an interrupt.			
			RXF = 0	Receiver is empty. This bit is cleared when MCU reads the I2CDAI register.			
			RXF = 1	Receiver contains new data. This bit is set by the I2C controller when the received serial data has been loaded into I2CDAI register			

2.10.2 I2CADR: I2C Address Register

This register holds the device address and the read/write command bit.

7	6	5	4	3	2	1	0
A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀	R/W
R/W	R/W						

BIT	NAME	RESET	FUNCTION
0	R/W	0	Read/write command bit. R/W = 0 Write operation R/W = 1 Read operation
7–1	A[6:0]	0000000	Seven address bits for device addressing.

2.10.3 I2CDAI: I2C Data-Input Register

This register holds the received data from an external device.

7	6	5	4	3	2	1	0
D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀
R/O							

BIT	NAME	RESET	FUNCTION
7–0	D[7:0]	0	8-bit input data from an I2C device

2.10.4 I2CDAO: I2C Data-Output Register

This register holds the data to be transmitted to an external device. Writing to this register starts the transfer on the SDA line.

7	6	5	4	3	2	1	0
D7	D6	D5	D4	D3	D2	D1	D0
R/W							

BIT	NAME	RESET	FUNCTION
7–0	D[7:0]	0	8-bit output data to an I2C device

2.11 Read/Write Operations

2.11.1 Read Operation (Serial EEPROM)

A serial read requires a *dummy* byte write sequence to load in the 16-bit data word address. Once the device address word and data word address is clocked out and acknowledged by the device, the MCU starts a current address sequence. The following describes the sequence of events to accomplish this transaction:

Device Address + EEPROM [High-byte]

- MCU sets I2CSTA[SRD] = 0. This forces the I2C controller not to generate a stop condition after the content of I2CDAI register is received.
- MCU sets I2CSTA[SWR] = 0. This forces the I2C controller to NOT generate a stop condition after the content of I2CDAO register is transmitted.
- MCU writes the device address (R/W bit = 0) to I2CADR register (write operation)
- MCU writes the High-Byte of the EEPROM address into I2CDAO register, starting the transfer on SDA line
- TXE bit in I2CSTA is cleared, indicating busy

- The content of I2CADR register is transmitted to the EEPROM (preceded by start condition on SDA)
- The content of I2CDAO register is transmitted to the EEPROM (EEPROM address)
- TXE bit in I2CSTA is set, and interrupts the MCU, indicating that I2CDAO register has been transmitted
- No stop condition is generated

EEPROM [Low-byte]

- MCU writes the Low-byte of the EEPROM address into I2CDAO register
- TXE bit in I2CSTA is cleared, indicating busy
- The content of I2CDAO register is transmitted to the device (EEPROM address)
- TXE bit in I2CSTA is set, and interrupts the MCU, indicating that I2CDAO register has been transmitted
- This completes the *dummy* write operation. At this point, the EEPROM address is set and the MCU can do a single or a sequential read operation.

2.11.2 Current Address Read Operation

Once the EEPROM address is set the MCU can read a single byte by executing the following steps:

- MCU sets I2CSTA[SRD] = 1, forcing the I2C controller to generate a stop condition after I2CDAI register is received.
- 2. MCU writes the device address (R/W bit = 1) to I2CADR register (read operation).
- 3. MCU writes a dummy byte to I2CDAO register, starting the transfer on SDA line
- 4. RXF bit in I2CSTA is cleared
- 5. The content of I2CADR register is transmitted to the device, preceded by start condition on SDA
- 6. Data from the EEPROM is latched in I2CDAI register (stop condition is transmitted)
- 7. RXF bit in I2CSTA is set, and interrupt the MCU, indicating that the data is available.
- 8. MCU reads I2CDAI register. This clears RXF bit (I2CSTA[RXF] = 0)
- 9. END

2.11.3 Sequential Read Operation

Once the EEPROM address is set, the MCU can execute a sequential read operation by executing the following steps (Note: this example illustrates 32-byte sequential read):

- 1. Device Address
 - MCU sets I2CSTA[SRD] = 0. This forces the I2C controller to not generate a stop condition after I2CDAI
 register is received
 - MCU writes the device address (R/W bit = 1) to I2CADR register (read operation)
 - MCU writes a dummy byte to I2CDAO register, starting the transfer on SDA line
 - RXF bit in I2CSTA is cleared
 - The content of I2CADR register is transmitted to the device (preceded by start condition on SDA)
- 2. N-Byte Read (31-bytes)
 - Data from the device is latched in I2CDAI register (stop condition is not transmitted)
 - RXF bit in I2CSTA is set, and interrupt the MCU, indicating that data is available

- MCU reads I2CDAI register, clearing RXF bit (I2CSTA[RXF] = 0)
- This operation repeats 31 times
- 3. Last-Byte read (byte No. 32)
 - MCU sets I2CSTA[SRD] = 1. This forces the I2C controller to generate a stop condition after I2CDAI
 register is received
 - Data from the device is latched in I2CDAI register (Stop condition is transmitted)
 - RXF bit in I2CSTA is set, and interrupt the MCU, indicating that data is available
 - MCU reads I2CDAI register, clearing RXF bit (I2CSTA[RXF] = 0)
 - END

2.11.4 Write Operation (Serial EEPROM)

Byte write operation involves three phases: 1) device address + EEPROM [High-byte] phase, 2) EEPROM [Low-byte] phase, and 3) EEPROM [DATA]. The following describes the sequence of events to accomplish the byte write transaction:

Device Address + EEPROM [High-byte]

- MCU sets I2CSTA[SWR] = 0. This forces the I2C controller to not generate a stop condition after the content of I2CDAO register is transmitted.
- MCU writes the device address (R/W bit = 0) to I2CADR register (write operation)
- MCU writes the high-byte of the EEPROM address into I2CDAO register, starting the transfer on SDA line
- TXE bit in I2CSTA is cleared, indicating busy
- The content of I2CADR register is transmitted to the device (preceded by start condition on SDA)
- The content of I2CDAO register is transmitted to the device (EEPROM high-address)
- TXE bit in I2CSTA is set, and interrupts the MCU, indicating that I2CDAO register has been transmitted

EEPROM [Low-byte]

- MCU writes the low-byte of the EEPROM address into I2CDAO register
- TXE bit in I2CSTA is cleared, indicating busy
- The content of I2CDAO register is transmitted to the device (EEPROM address)
- TXE bit in I2CSTA is set, and interrupts the MCU, indicating that I2CDAO register has been transmitted

EEPROM [DATA]

- MCU sets I2CSTA[SWR] = 1. This forces the I2C controller to generate a stop condition after the content
 of I2CDAO register is transmitted.
- MCU writes the DATA to be written to the EEPROM into I2CDAO register
- TXE bit in I2CSTA is cleared, indicating busy
- The content of I2CDAO register is transmitted to the device (EEPROM data)
- TXE bit in I2CSTA is set, and interrupts the MCU, indicating that I2CDAO register has been transmitted
- I2C controller generates a stop condition after the content of I2CDAO register is transmitted
- END

2.11.5 Page Write Operation

Page write operation is initiated the same way as byte write, with the exception that stop condition is not generated after the first EEPROM [DATA] is transmitted. The following describes the sequence of writing 32-bytes in page mode:

Device Address + EEPROM [High-byte]

- MCU sets I2CSTA[SWR] = 0. This forces the I2C controller to not generate a stop condition after the content
 of I2CDAO register is transmitted.
- MCU writes the device address (R/W bit = 0) to I2CADR register (write operation)
- MCU writes the high-byte of the EEPROM address into I2CDAO register.
- TXE bit in I2CSTA is cleared, indicating busy
- The content of I2CADR register is transmitted to the device (preceded by start condition on SDA)
- The content of I2CDAO register is transmitted to the device (EEPROM address)
- TXE bit in I2CSTA is set, and interrupt the MCU, indicating that I2CDAO register has been sent.

EEPROM [Low-byte]

- MCU writes the low-byte of the EEPROM address into I2CDAO register
- TXE bit in I2CSTA is cleared, indicating busy
- The content of I2CDAO register is transmitted to the device. (EEPROM address)
- TXE bit in I2CSTA is set, and interrupts the MCU, indicating that I2CDAO register has been sent.

31 Bytes EEPROM [DATA]

- MCU writes the DATA to be written to the EEPROM into I2CDAO register
- TXE bit in I2CSTA is cleared, indicating busy
- The content of I2CDAO register is transmitted to the device (EEPROM data)
- TXE bit in I2CSTA is set, and interrupts the MCU, indicating that I2CDAO register has been sent.
- This operation repeats 31 times.

Last Byte EEPROM [DATA]

- MCU sets I2CSTA[SWR] = 1. This forces the I2C controller to generate a stop condition after the content of I2CDAO register is transmitted.
- MCU writes the last DATA byte to be written to the EEPROM into I2CDAO register
- TXE bit in I2CSTA is cleared, indicating busy
- The content of I2CDAO register is transmitted to the EEPROM (EEPROM data)
- TXE bit in I2CSTA is set, and interrupts the MCU, indicating that I2CDAO register has been sent
- I2C controller generates a stop condition after the content of I2CDAO register is transmitted
- END of 32-byte page write operation

3 Electrical Specifications

3.1 Absolute Maximum Ratings Over Operating Free-Air Temperature (unless otherwise noted)[†]

Supply voltage, V _{CC}	0.5 V to 4 V
Input voltage, V _I	0.5 V to V _{CC} + 0.5 V
Output voltage, VO	\dots -0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK}	±20 mA
Output clamp current, I _{OK}	±20 mA
Storage temperature	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

3.2 Commercial Operating Condition

	PARAMETER	MIN	NOM	MAX	UNIT
VCC	Supply voltage	3	3.3	3.6	V
٧ _I	Input voltage	0		VCC	V
V_{IH}	High level input voltage	2		VCC	V
V_{IL}	Low level input voltage	0		8.0	V
TA	Operating temperature	0		70	°C

3.3 Electrical Characteristics, T_A = 25°C, V_{CC} = 3.3 V \pm 0.3V, GND = 0 V

	PARAMETER	TEST CONDITIONS	MIN	NOM	MAX	UNIT
Vон	High-level output voltage	$I_{OH} = -4 \text{ mA}$	V _{CC} -0.5			V
VOL	Low-level output voltage	$I_{OL} = 4 \text{ mA}$			0.5	V
V _{IT+}	Positive input threshold voltage	$V_I = V_{IH}$			2	V
V _{IT} _	Negative input threshold voltage	$V_I = V_{IH}$	0.8			V
V _{hys}	Hysteresis (V _{IT+} – V _{IT-})	$V_I = V_{IH}$		1		V
ΙΗ	High-level input current	$V_I = V_{IH}$			±1	μΑ
I _{IL}	Low-level input current	$V_I = V_{IL}$			±1	μΑ
loz	Output Leakage Current (Hi-Z)	$V_I = V_{CC}$ or V_{SS}			10	μΑ
Cl	Input capacitance			5		pF
CO	Output capacitance			7		pF
ICC	Quiescent			25	45	mA
ICCx	Suspend			45		μΑ

4 Application

4.1 Examples

Figure 4–1 illustrates the Port-3 pins that are assigned to drive the four example LEDs. For the connection example shown, P3[7:4] can sink up to 12 mA (open-drain output). Figure 4–2 illustrates the partial connection bus power mode. Figure 4–3 shows the USB upstream connection, and Figure 4–4 illustrates the downstream connection (only one port shown).

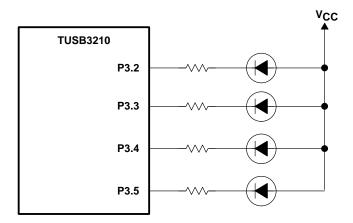


Figure 4-1. Example LED Connection

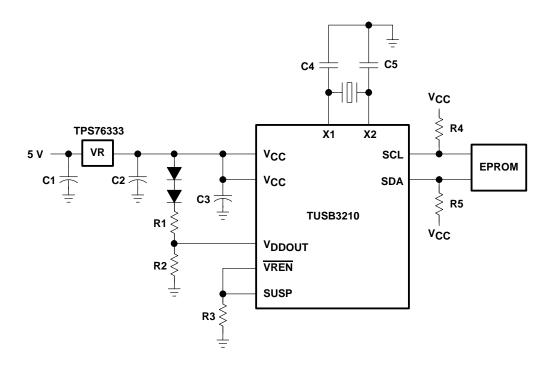


Figure 4–2. Partial Connection Bus Power Mode

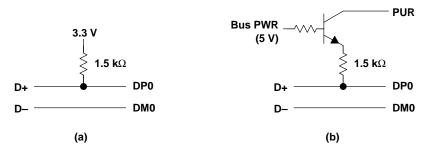
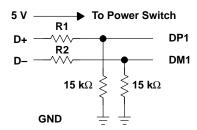


Figure 4-3. Upstream Connection (a) Non-Switching Power Mode (b) Switching Power Mode



NOTE: Ferrite beads can be used on power lines to help ESD.

Figure 4-4. Downstream Connection - (Only One Port Shown)

4.2 Reset Timing

There are two requirements for the reset signal timing. First, the reset window should be between 100 μ sec and 10 msec. At power up, this time is measured from the time the power ramps up to 90% of the nominal Vcc until the reset signal goes high (above 1.2 V). The second requirement is that the clock has to be valid during the last 60 μ sec of the reset window. These two requirements are depicted in Figure 4–5. Notice that when using a 12 MHz crystal or the 48 MHz oscillator, the clock signal may take several milliseconds to ramp up and become valid after power up. Therefore, the reset window may need to be elongated up to 10 msec. to ensure that there is a 60 μ sec overlap with a valid clock.

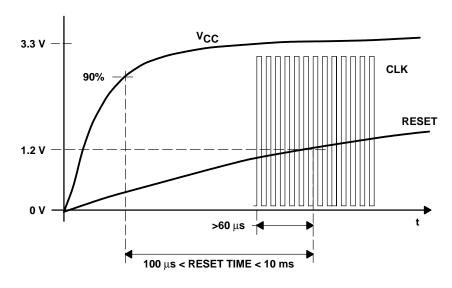
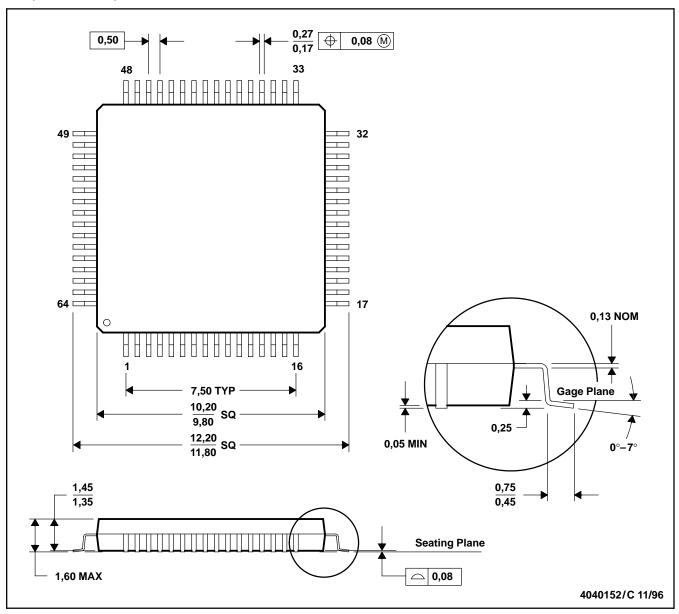


Figure 4-5. Reset Timing

5 Mechanical Data

PM (S-PQFP-G64)

PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-026
- D. May also be thermally enhanced plastic with leads connected to the die pads.

Copyright © Each Manufacturing Company.

All Datasheets cannot be modified without permission.

This datasheet has been download from:

www.AllDataSheet.com

100% Free DataSheet Search Site.

Free Download.

No Register.

Fast Search System.

www.AllDataSheet.com